

Title (en)

ELECTRICAL COMPONENT WITH THIN SOLDER RESIST LAYER AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

ELEKTRISCHES BAUELEMENT MIT DÜNNER LOT-STOPP-SCHICHT UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

ÉLÉMENT ÉLECTRIQUE AVEC UNE COUCHE MINCE D'ARRÊT DE SOUDURE ET SON PROCÉDÉ DE FABRICATION

Publication

**EP 3381052 A1 20181003 (DE)**

Application

**EP 16762778 A 20160906**

Priority

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Abstract (en)

[origin: WO2017088998A1] The invention relates to an electrical module (EB) and to a method for producing an electrical module (EB). The module (EB) has a substrate (TR) with an upper layer (O) and a metal contact surface (MK) arranged thereon, as well as a solder resist layer (LSS) that covers part of the upper side (O), but not the contact surface (MK). The module (EB) also comprises an electrical component (EK) with a contact surface (KF) on the lower side and a solder bump connection (BU) that connects the two contact surfaces (MK, KF). The solder resist layer (O) has a maximum thickness of 200 nm and thereby simplifies subsequent method steps for the encapsulation of the module (EB) with a mould mass (MM).

IPC 8 full level

**H01L 23/498** (2006.01); **B81C 3/00** (2006.01); **H01L 21/56** (2006.01); **H01L 21/60** (2006.01); **H01L 23/485** (2006.01)

CPC (source: EP KR US)

**H01L 21/4846** (2013.01 - KR US); **H01L 21/4853** (2013.01 - US); **H01L 21/56** (2013.01 - EP US); **H01L 21/565** (2013.01 - US); **H01L 23/3121** (2013.01 - EP KR US); **H01L 23/49811** (2013.01 - US); **H01L 23/49838** (2013.01 - US); **H01L 23/49894** (2013.01 - EP KR US); **H01L 24/02** (2013.01 - EP KR US); **H01L 24/11** (2013.01 - EP KR US); **H01L 24/14** (2013.01 - KR); **H01L 24/16** (2013.01 - EP US); **H01L 24/81** (2013.01 - EP KR US); **H01L 24/05** (2013.01 - EP US); **H01L 24/13** (2013.01 - EP US); **H01L 2224/02375** (2013.01 - EP US); **H01L 2224/0239** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2224/10145** (2013.01 - EP US); **H01L 2224/10175** (2013.01 - EP US); **H01L 2224/1132** (2013.01 - EP US); **H01L 2224/1148** (2013.01 - EP US); **H01L 2224/11849** (2013.01 - EP US); **H01L 2224/131** (2013.01 - EP US); **H01L 2224/13294** (2013.01 - EP US); **H01L 2224/133** (2013.01 - EP US); **H01L 2224/16058** (2013.01 - EP US); **H01L 2224/16059** (2013.01 - EP US); **H01L 2224/16145** (2013.01 - EP US); **H01L 2224/16227** (2013.01 - US); **H01L 2224/16238** (2013.01 - EP US); **H01L 2224/81192** (2013.01 - EP US); **H01L 2224/81815** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/3841** (2013.01 - EP US)

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See references of WO 2017088998A1

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BA ME

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DOCDB simple family (application)

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